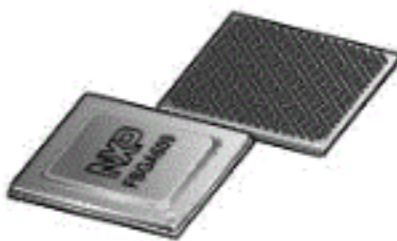


MIMX8UX5FVLFZAC

ACTIVE

OverviewOperating FeaturesEnvironmentalQualityShippingProduct Change Notice

BUY OPTIONS



Click to expand

Package

FBGA609: FBGA609, fine-pitch ball grid array package; 609 terminals, 0.8 mm pitch, 21 mm x 21 mm x 2.37 mm body



Buy Options

MIMX8UX5FVLFZAC ACTIVE

12NC: 935407673557

Details

- Packing: TRAY-Tray, Bakeable, Multiple in Drypack
- Min. Package Quantity: 60
- Min. Order Quantity: 60
- Lead Time: 26 weeks
- Budgetary Price: 1K at \$57.68 USD

Order

[Order from distributors](#)

[Order from distributors](#)

Operating Features

No information available

Environmental

Part/12NC	PbFree	EU RoHS	Halogen Free	RHF Indicator	REACH SVHC	Weight (mg)
MIMX8UX5FVLFZAC(935407673557)	Yes	Yes Certificate Of Analysis (CoA)	Yes	D	REACH SVHC	3081.5

Quality

Part/12NC	Safe Assure Functional Safety	Moisture Sensitivity Level (MSL)	Peak Package Body Temperature (PPT) (C°)	Maximum Time at Peak Temperatures (s)
		Lead Free Soldering	Lead Free Soldering	Lead Free Soldering
MIMX8UX5FVLFZAC (935407673557)	No	3	260	40

Shipping

Part/12NC	Harmonized Tariff (US)Disclaimer	Export Control Classification Number (US)	CCATS
MIMX8UX5FVLFZAC (935407673557)	854231	5A992C	G170338

Product Change Notice

Part/12NC	Issue Date	Effective Date	PCN	Title
MIMX8UX5FVLFZAC (935407673557)	2025-04-16	2025-05-26	202504007I	Freescle Logo to NXP Logo Product Marking Conversion for All Remaining Former Freescle Products
MIMX8UX5FVLFZAC (935407673557)	2023-04-21	2023-04-22	20230303II	i.MX 8X Errata Rev 3.1 1N95W and 0N99Z
MIMX8UX5FVLFZAC (935407673557)	2020-12-15	2020-12-16	20201101II	NXP Will Add a Sealed Date to the Product Label

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